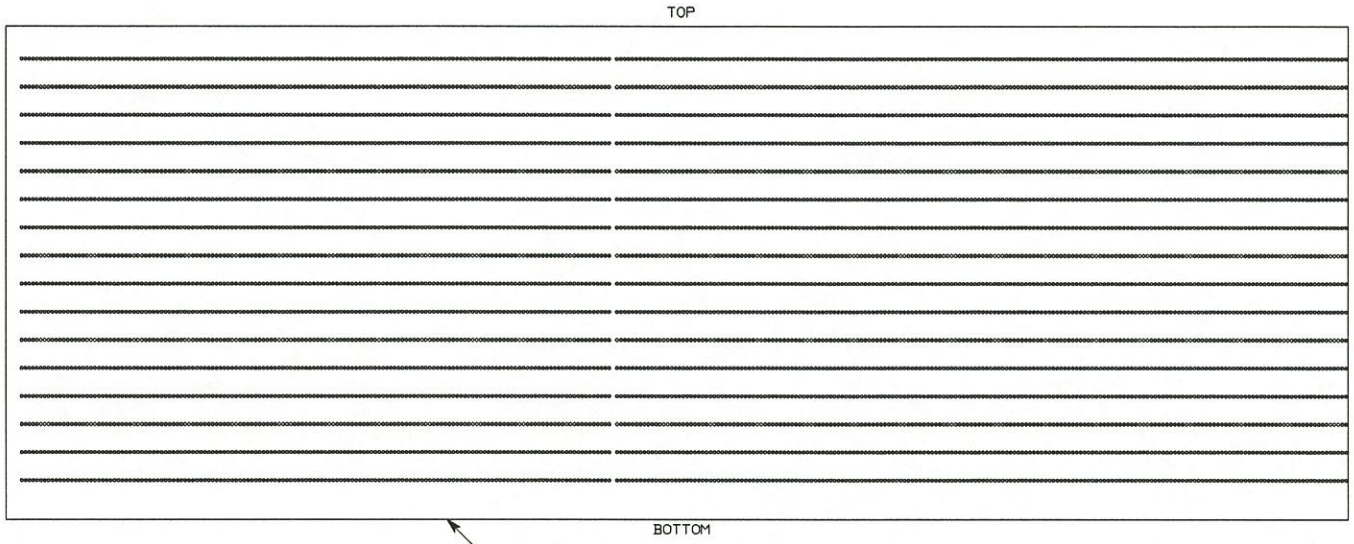
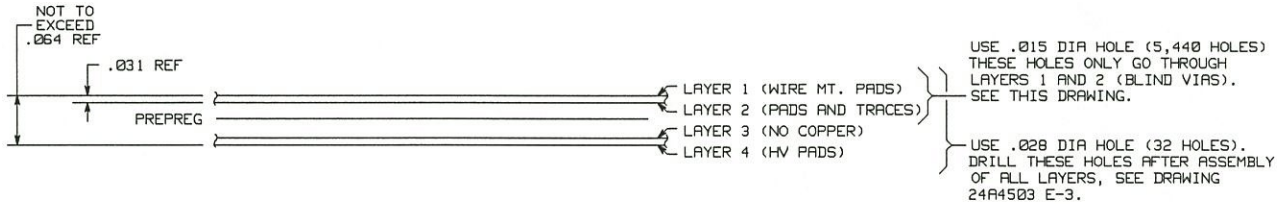
REV.	CHANGES	DRAWN	DATE	CHKD.	DATE

LAYER TWO VIEW

SCALE: NONE





NOTES:

1. BOARD MATERIAL: .031 THICK G10 PER MIL-P-55617 FL-GEN 031C-1/1-A1A (1 OZ. COPPER EACH SIDE). THIS IS A MULTILAYER BOARD (4 LAYERS). TOTAL THICKNESS NOT TO EXCEED .064.
2. PLEASE NOTE THAT THERE IS NO COPPER ON LAYER 3.
3. THIS BOARD TO BE THROUGH HOLE PLATED.
4. SPECIFIED HOLE DIA. SIZES ARE FOR FINISHED HOLES AFTER PLATING.
5. BOARD SIZE IS 10.500 +/-.010 X 28.100 +/-.005. DIMENSIONS ARE IN INCHES. BOARD OUTLINE DRAWING IS 24A4503 M-2 (a000896m2).
6. SOLDERMASK IS NOT USED ON THIS BOARD.
7. REFERENCE DRAWINGS:

24A4502 M-1	a000896m1	BOARD OUTLINE - SINGLE BOARD
24A4503 M-2	a000896m2	BOARD OUTLINE - PANEL OF 16
24A4502 E-1	a000896e1	HOLE SCHEDULE - SINGLE BOARD
24A4503 E-3	a000896e3	HOLE SCHEDULE - PANEL OF 16

HOLE SCHEDULE		
CODE	HOLE DIA.	COUNT
NONE	.015	5,440

DIST I:		TITLE	STAR TPC		
DIST II:			INNER SECTOR ELECTRONICS		
DIST III:			GATED GRID WIRE MOUNT BOARD - PANEL 0F 16		
SHOWN ON			HOLE SCHEDULE - 24A4501 U-2 (BLIND VIAS)		
ACCOUNT NUMBER	8052-24	DRAWN STIRKKINEN	DATE 4/08/94	LAWRENCE BERKELEY LABORATORY	
SERIAL NUMBER		CHECKED	DATE	UNIVERSITY OF CALIFORNIA	
DATE ISSUED	NO. REQD.	APPROVED	DATE	OFFICE OF ELECTRONICS ENGINEERING	
DATE REQD.		ENGINEER JIM HUNTER		FILE NO. a000896e2 / SIZE 3 / DRAWING NO. 24A4503 E-2	REV.
DEL. TO		SCALE NONE		C8,E14	SHEET 2 OF 3